IPA90R340C3XKSA1 Datasheet

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DiGi Electronics Part Number	IPA90R340C3XKSA1-DG
Manufacturer	Infineon Technologies
Manufacturer Product Number	IPA90R340C3XKSA1
Description	MOSFET N-CH 900V 15A TO220-FP
Detailed Description	N-Channel 900 V 15A (Tc) 35W (Tc) Through Hole PG-TO220-FP

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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
IPA90R340C3XKSA1	Infineon Technologies
Series:	Product Status:
CoolMOS™	Obsolete
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
900 V	15A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
10V	340mOhm @ 9.2A, 10V
Vgs(th) (Max) @ Id:	Gate Charge (Qg) (Max) @ Vgs:
3.5V @ 1mA	94 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±20V	2400 pF @ 100 V
FET Feature:	Power Dissipation (Max):
-	35W (Tc)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Through Hole
Supplier Device Package:	Package / Case:
PG-TO220-FP	TO-220-3 Full Pack
Base Product Number:	
IPA90R	

Environmental & Export classification

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8541.29.0095	

IPA90R340C3

CoolMOS™ Power Transistor

Features

- Lowest figure-of-merit R_{ON} x Q_g
- Extreme dv/dt rated
- High peak current capability
- Qualified according to JEDEC[1)] for target applications
- Pb-free lead plating; RoHS compliant
- Worldwide best $R_{DS,on}$ in TO220 Fullpak
- Ultra low gate charge

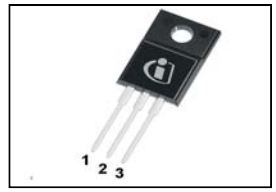
CoolMOS™ 900V is designed for:

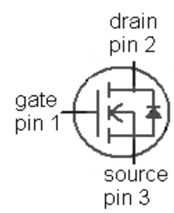
- Quasi Resonant Flyback / Forward topologies
- PC Silverbox and consumer applications
- Industrial SMPS

Product Summary

V_{DS} @ T_J=25°C	900	V
$R_{DS(on),max}$ @ T_J = 25°C	0.34	Ω
$Q_{g,typ}$	94	nC

PG-TO220 FP





Type	**Package**	**Marking**
IPA90R340C3	PG-TO220 FP	9R340C

Maximum ratings, at T_J=25 °C, unless otherwise specified

Parameter	**Symbol**	**Conditions**	**Value**	**Unit**
Continuous drain current[2)]	I_D	T_C=25 °C	15	A
		T_C=100 °C	9.5	
Pulsed drain current[3)]	$I_{D,pulse}$	T_C=25 °C	34	
Avalanche energy, single pulse	E_{AS}	I_D=3.1 A, V_{DD}=50 V	678	mJ
Avalanche energy, repetitive t_{AR}[3),4)]	E_{AR}	I_D=3.1 A, V_{DD}=50 V	1	
Avalanche current, repetitive t_{AR}[3),4)]	I_{AR}		3.1	A
MOSFET dv/dt ruggedness	dv/dt	V_{DS}=0...400 V	50	V/ns
Gate source voltage	V_{GS}	static	±20	V
		AC (f>1 Hz)	±30	
Power dissipation	P_{tot}	T_C=25 °C	35	W
Operating and storage temperature	T_J, T_{stg}		-55 ... 150	°C
Mounting torque		M2.5 screws	50	Ncm

Maximum ratings, at T_J=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous diode forward current[2)]	I_S	T_C=25 °C	9.2	A
Diode pulse current[3)]	$I_{S,pulse}$		34	
Reverse diode dv/dt[5)]	dv/dt		4	V/ns

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics						
Thermal resistance, junction - case	R_{thJC}		-	-	3.6	K/W
Thermal resistance, junction - ambient	R_{thJA}	leaded	-	-	62	
Soldering temperature, wavesoldering only allowed at leads	T_{sold}	1.6 mm (0.063 in.) from case for 10 s	-	-	260	°C

Electrical characteristics, at T_J=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D=250 µA	900	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=1 mA	2.5	3	3.5	
Zero gate voltage drain current	I_{DSS}	V_{DS}=900 V, V_{GS}=0 V, T_j=25 °C	-	-	2	µA
		V_{DS}=900 V, V_{GS}=0 V, T_j=150 °C	-	20	-	
Gate-source leakage current	I_{GSS}	V_{GS}=20 V, V_{DS}=0 V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10 V, I_D=9.2 A, T_j=25 °C	-	0.28	0.34	Ω
		V_{GS}=10 V, I_D=9.2 A, T_j=150 °C	-	0.76	-	
Gate resistance	R_G	f=1 MHz, open drain	-	1.3	-	Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=100 V, f=1 MHz	-	2400	-	pF
Output capacitance	C_{oss}		-	120	-	
Effective output capacitance, energy related [6]	$C_{o(er)}$	V_{GS}=0 V, V_{DS}=0 V to 500 V	-	71	-	
Effective output capacitance, time related [7]	$C_{o(tr)}$		-	280	-	
Turn-on delay time	$t_{d(on)}$	V_{DD}=400 V, V_{GS}=10 V, I_D=9.2A, R_G=23.1 Ω	-	70	-	ns
Rise time	t_r		-	20	-	
Turn-off delay time	$t_{d(off)}$		-	400	-	
Fall time	t_f		-	25	-	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	V_{DD}=400 V, I_D=9.2 A, V_{GS}=0 to 10 V	-	11	-	nC
Gate to drain charge	Q_{gd}		-	41	-	
Gate charge total	Q_g		-	94	tbd	
Gate plateau voltage	$V_{plateau}$		-	4.6	-	V
Reverse Diode						
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=9.2 A, T_j=25 °C	-	0.8	1.2	V
Reverse recovery time	t_{rr}	V_R=400 V, I_F=I_S, di_F/dt=100 A/µs	-	510	-	ns
Reverse recovery charge	Q_{rr}		-	11	-	µC
Peak reverse recovery current	I_{rrm}		-	41	-	A

[1] J-STD20 and JESD22

[2] Limited only by maximum temperature

[3] Pulse width t_p limited by $T_{J,max}$

[4] Repetitive avalanche causes additional power losses that can be calculated as $P_{AV}=E_{AR}*f$.

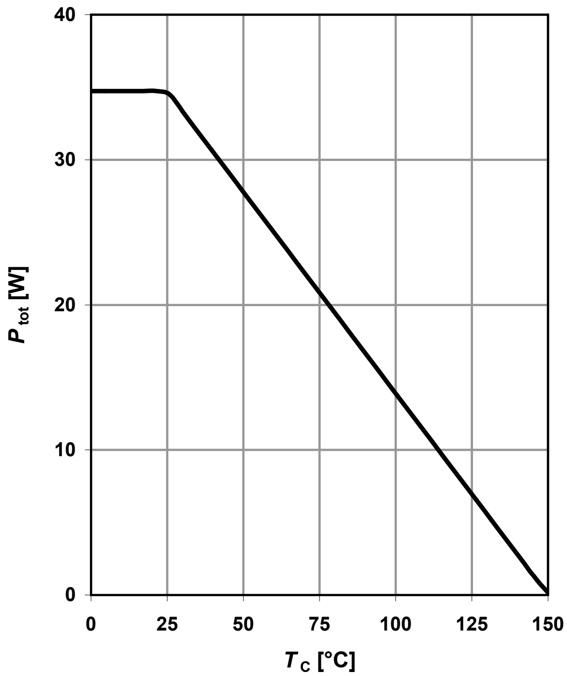
[5] $I_{SD} \leq I_D$, di/dt≤200 A/µs, V_{DClink}=400V, $V_{peak}<V_{(BR)DSS}$, $T_J<T_{J,max}$, identical low side and high side switch

[6] $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 50% V_{DSS}.

[7] $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 50% V_{DSS}.

1 Power dissipation

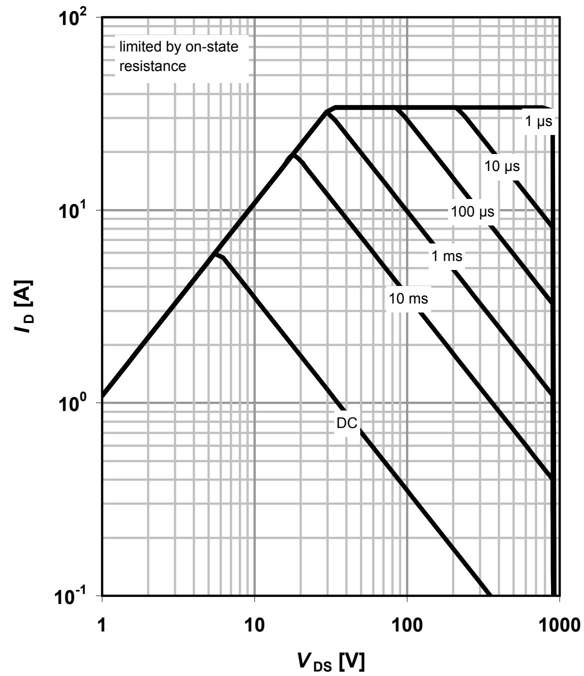
P_{tot}=f(T_C)



2 Safe operating area

I_D=f(V_{DS}); T_C=25 °C; D=0

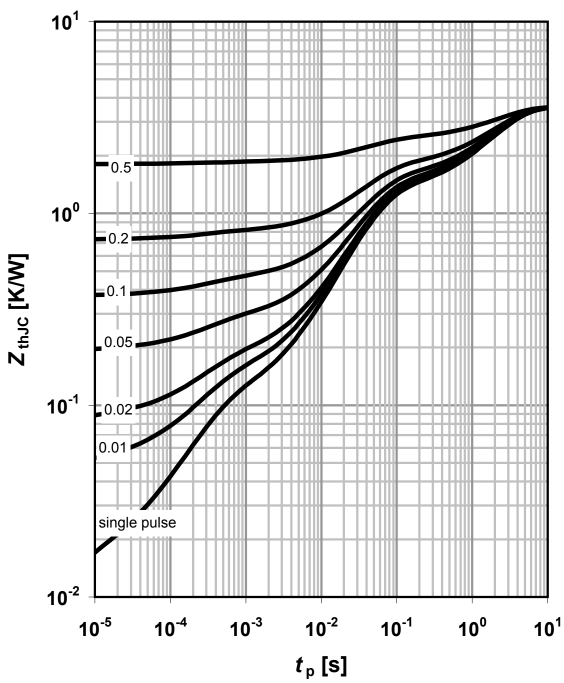
parameter: t_p



3 Max. transient thermal impedance

Z_{thJC}=f(t_P)

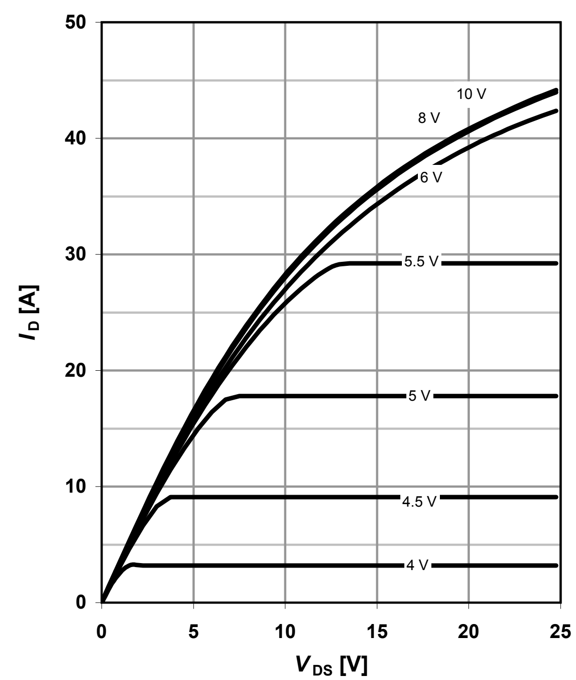
parameter: D=t_p/T



4 Typ. output characteristics

I_D=f(V_{DS}); T_J=25 °C

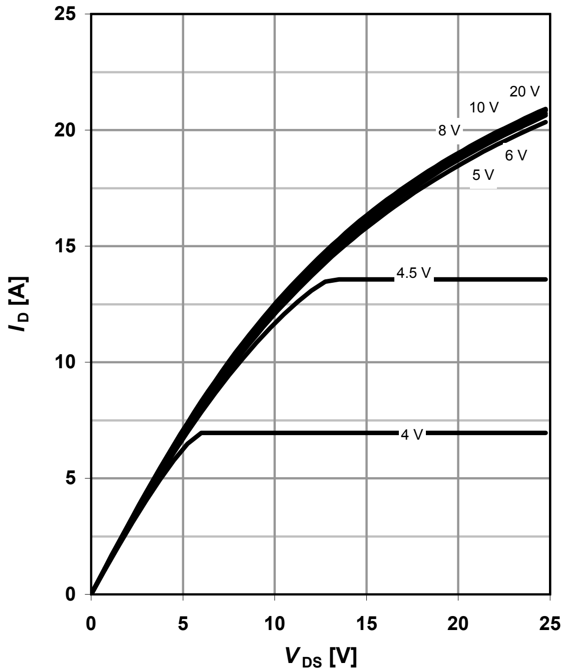
parameter: V_{GS}



5 Typ. output characteristics

I_D=f(V_{DS}); T_J=150 °C

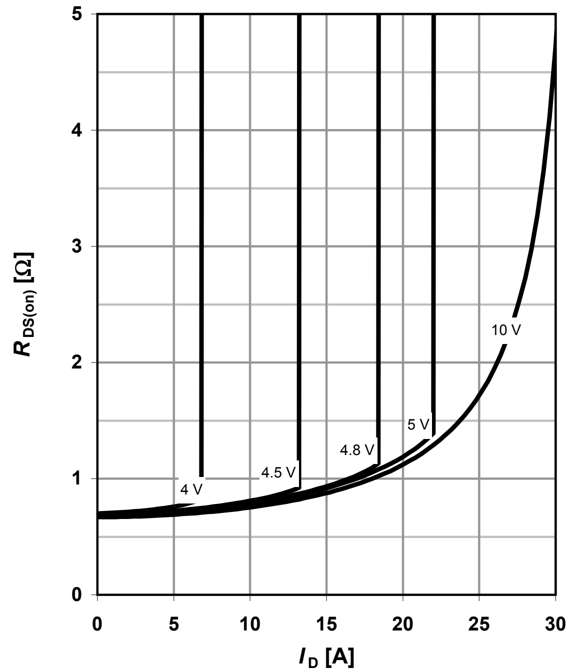
parameter: V_{GS}



6 Typ. drain-source on-state resistance

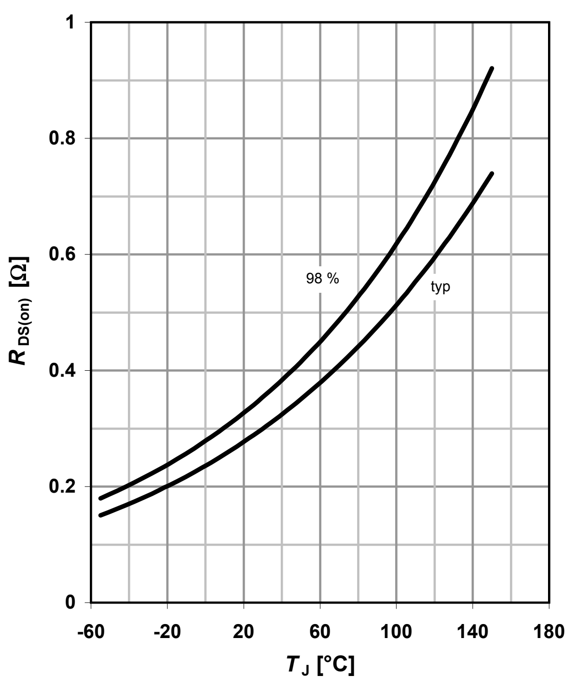
$R_{DS(on)}$=f(I_D); T_J=150 °C

parameter: V_{GS}



7 Drain-source on-state resistance

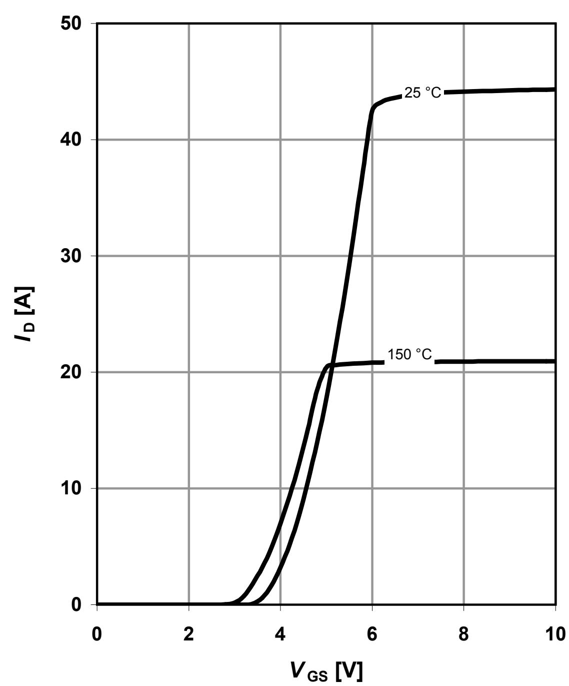
$R_{DS(on)}$=f(T_J); I_D=9.2 A; V_{GS}=10 V



8 Typ. transfer characteristics

I_D=f(V_{GS}); V_{DS}=20V

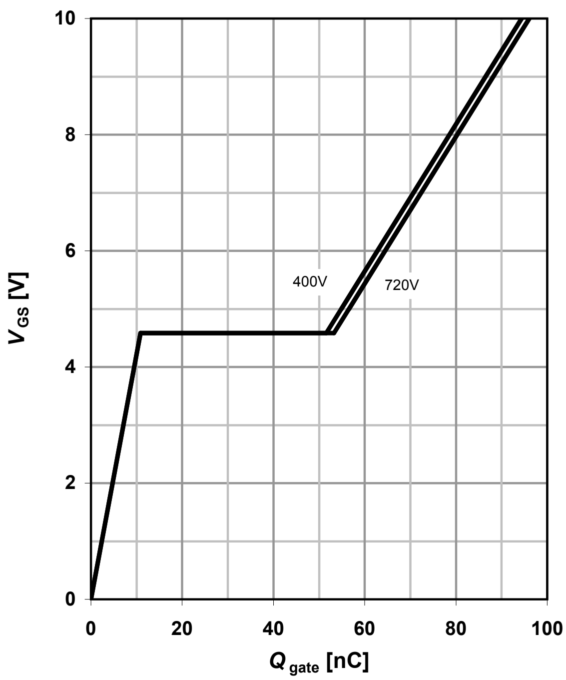
parameter: T_J



9 Typ. gate charge

V_{GS}=f(Q_{gate}); I_D=9.2 A pulsed

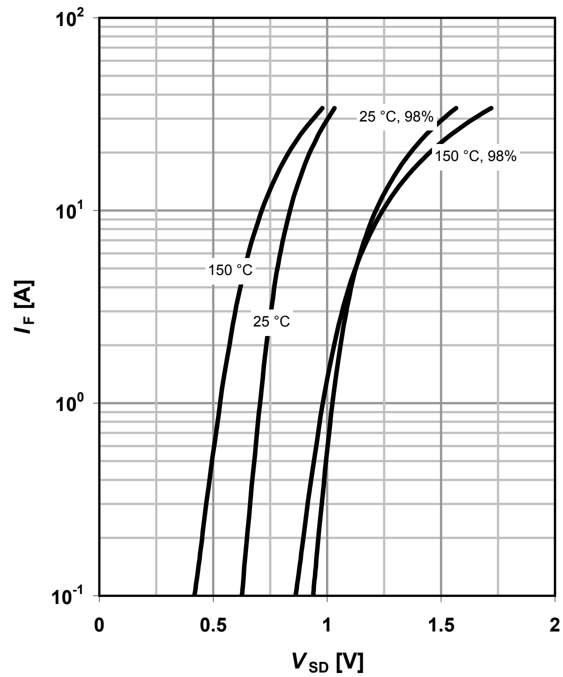
parameter: V_{DD}



10 Forward characteristics of reverse diode

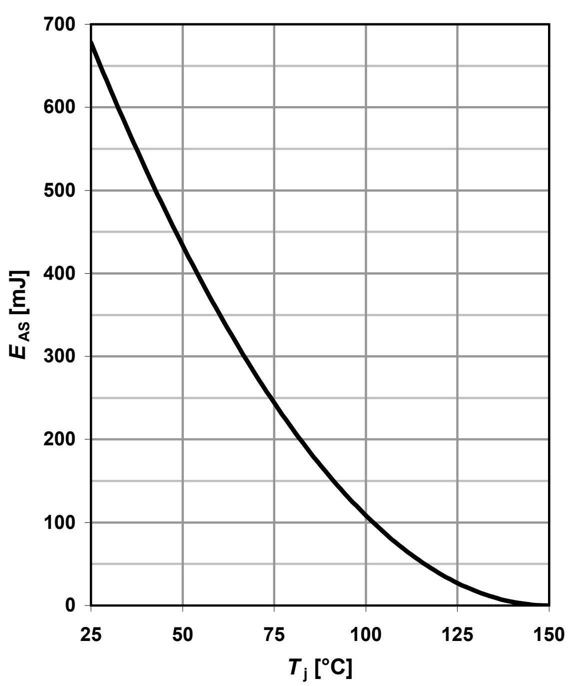
I_F=f(V_{SD})

parameter: T_J



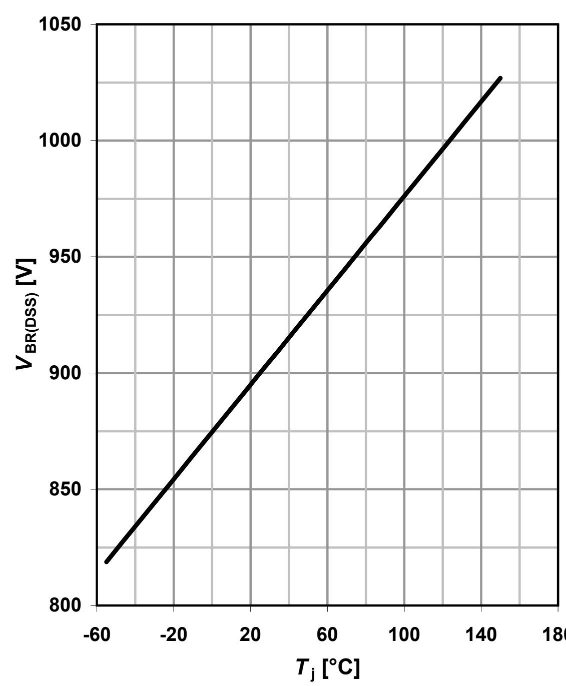
11 Avalanche energy

E_{AS}=f(T_j); I_D=3.1A; V_{DD}=50 V



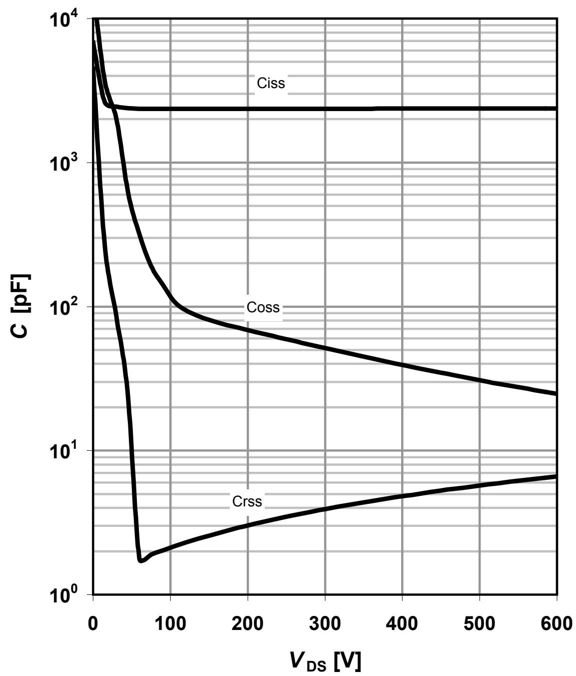
12 Drain-source breakdown voltage

$V_{BR(DSS)}$=f(T_j); I_D=0.25 mA



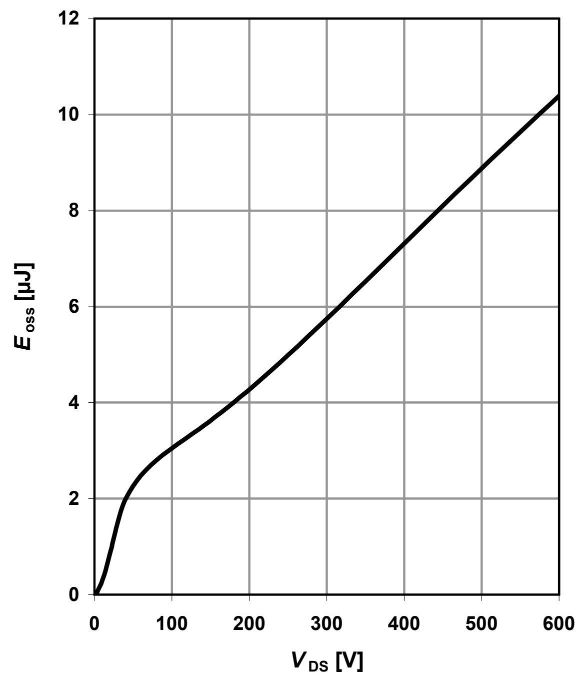
13 Typ. capacitances

$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz

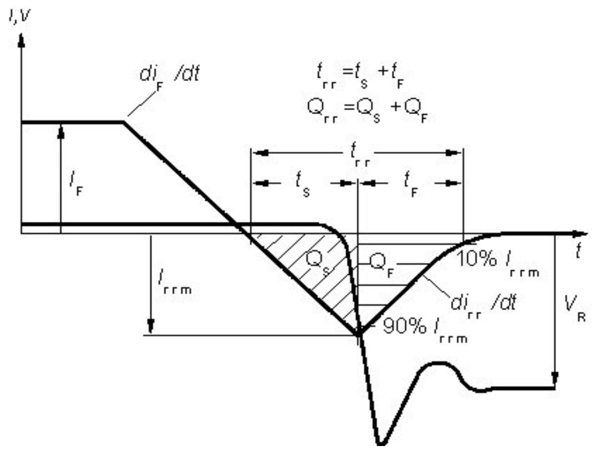


14 Typ. C_{oss} stored energy

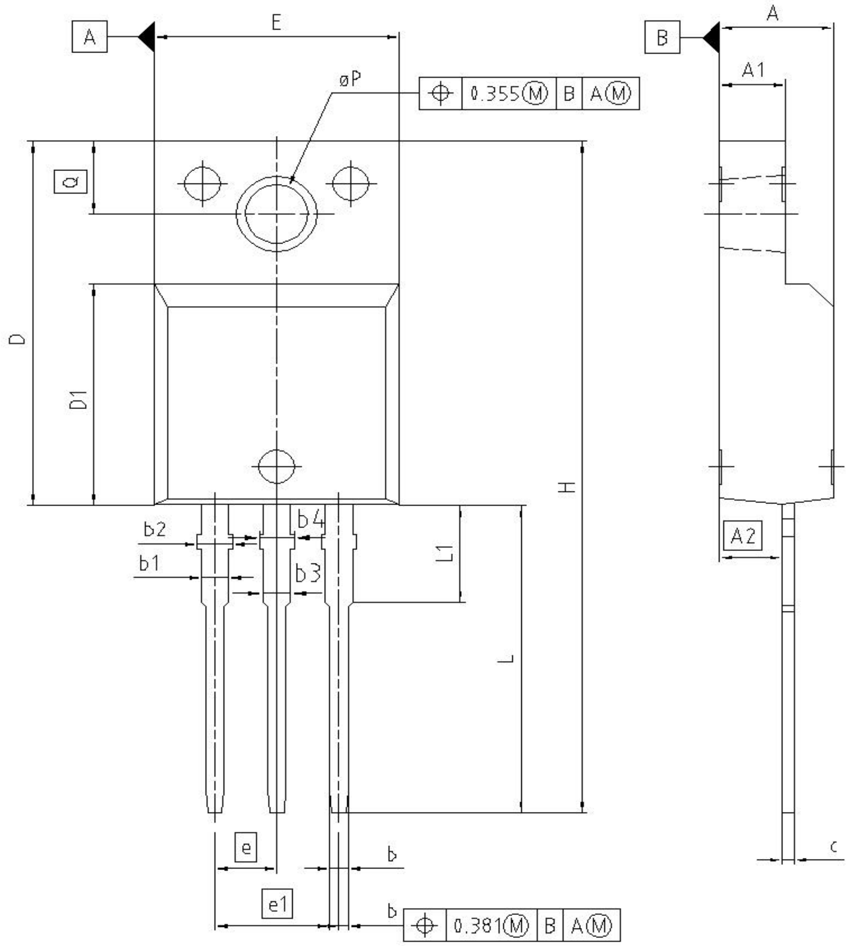
$E_{oss} = f(V_{DS})$



Definition of diode switching characteristics



PG-TO220 FP Outline/Fully isolated package (2500VAC; 1minute)



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.55	4.85	0.179	0.191
A1	2.55	2.85	0.100	0.112
A2	2.42	2.72	0.095	0.107
b	0.65	0.85	0.026	0.033
b1	0.95	1.33	0.037	0.052
b2	0.95	1.51	0.037	0.059
b3	0.65	1.33	0.026	0.052
b4	0.65	1.51	0.026	0.059
c	0.40	0.63	0.016	0.025
D	15.85	16.15	0.624	0.636
D1	9.53	9.83	0.375	0.387
E	10.35	10.65	0.407	0.419
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H	29.45	29.75	1.159	1.171
L	13.45	13.75	0.530	0.541
L1	3.15	3.45	0.124	0.136
øP	2.95	3.20	0.116	0.126
Q	3.15	3.50	0.124	0.138

REFERENCE
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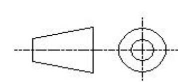
SCALE
0
2.5
0
2.5
5mm

EUROPEAN PROJECTION



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FILE
TO220_2

Dimensions in mm/inches

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